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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventive Patent Application of

Takeshi OOTSUKA, et al.

Date: September 23, 2004

Serial No.: 10/668,483

Group Art Unit: 2823

Filed: September 22, 2003

Examiner: Julio J. MALDONADO

For: BONDING METHOD, BONDING STAGE AND ELECTRONIC
COMPONENT PACKAGING APPARATUSMail Stop Amentment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**RESPONSE TO RESTRICTION REQUIREMENT**
REMARKS/ARGUMENT

This Response is filed in reply to the Restriction Requirement mailed September 2, 2004. Applicant elects the invention of Group II: Claims 3-13, drawn to a semiconductor manufacturing device apparatus, classified in Class 156, subclass 345.39.

Applicant reserves the right to file a divisional application directed to the subject matter covered in the non-elected claims 1 and 2.

Early and favorable consideration of the present application is earnestly solicited.

If this communication is filed after the statutory time period had elapsed and no separate Petition is enclosed, the Commissioner for Patents is petitioned, under 37 C.F.R. § 1.136(a), to extend the time for filing a response to the outstanding Office Action by the number of months which will avoid abandonment under 37 C.F.R. § 1.135. The fee under 37 C.F.R. § 1.17 should be charged to our Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 23, 2004

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Name of applicant, assignee or
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Signature

September 23, 2004

Date of Signature

Respectfully submitted,

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